



SF2039B-2

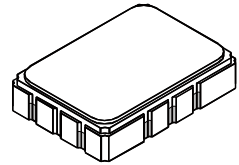
**72.540 MHz
SAW Filter**

- **Designed for SDARS IF Receiver**
- **Low Insertion Loss**
- **5.0 X 7.0 mm Surface-Mount Case**
- **Differential or Single Ended Input and Output**
- **Complies with Directive 2002/95/EC (RoHS)**



Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Max. DC voltage between any 2 terminals	30	VDC
Storage Temperature Range (with tape & reel)	-40 to +85	°C
Storage Temperature Range (without tape & reel)	-50 to +125	°C
Max Soldering Profile	265°C for 10 s	



SMP-03

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Nominal Center Frequency	f_c	1	72.540			MHz
Passband	Insertion Loss	1		10.5	12.5	dB
	1dB Passband		3.7	4.0		MHz
	15dB Bandwidth			6.5	6.7	MHz
	30dB Bandwidth			7.5	7.7	MHz
	Amplitude Ripple over $f_c \pm 1.85$ MHz			0.5	1.3	dB _{P-P}
	Group Delay Variation over $f_c \pm 1.85$ MHz	GDV		60	150	ns _{P-P}
Rejection	50 to 66.48 MHz	1, 3	40	47		dB
	66.48 to 68.08 MHz		30.5	43		
	77.30 to 78.60 MHz		38	42		
	78.60 to 86.50 MHz		40	44		
	86.50 to 91.50 MHz		45	50		
	91.50 to 100.00 MHz		45	55		
Operating Temperature Range	T_A	1	-40		+105	°C
Frequency Temperature Coefficient	FTC			-18		ppm/°C
Differential Input			175 ohms			
Differential Output			1000 ohms			
Case Style		6	SMP-03 7 x 5 mm Nominal Footprint			
Lid Symbolization (YY=year, WW=week, S=shift) See note 4			RFM SF2039B YYWWS			

Electrical Connections

Connection	Terminals
Port 1 Hot	10
Port 1 Ground Return	1
Port 2 Hot	5
Port 2 Ground Return	6
Case Ground	All Others

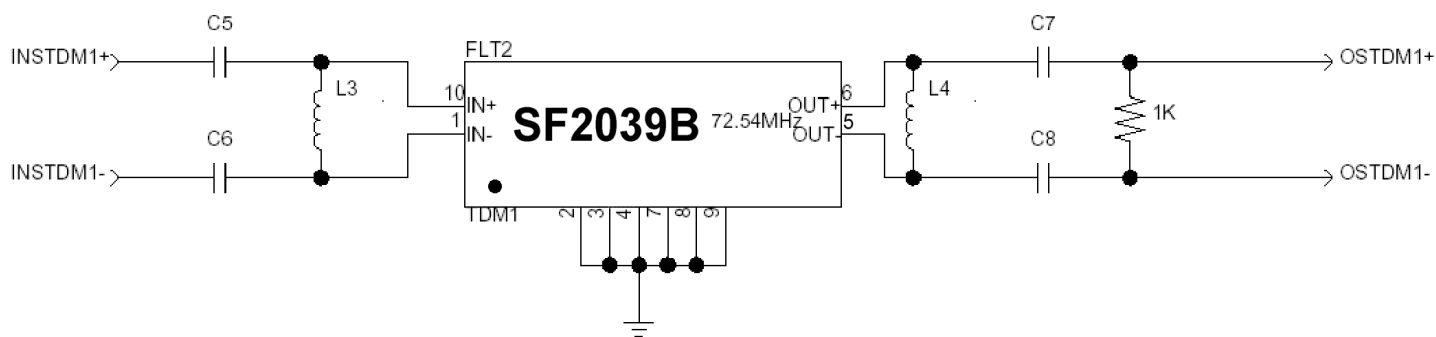
Notes:

1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, f_c .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Tape and Reel Standard ANSI / EIA 481.
7. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
8. US and international patents may apply.
9. RFM, stylized RFM logo, and RF Monolithics, Inc. are registered trademarks of RF Monolithics, Inc.
10. ©Copyright 1999, RF Monolithics Inc.
11. Electrostatic Sensitive Device. Observe precautions for handling.



Matching Circuit and Matching Component Values Used in G3 Sirius Radios

(Refer to Sirius Radio G3 Chipset Application Note, Doc. #RX000104-B, Sec. 4.2.3)

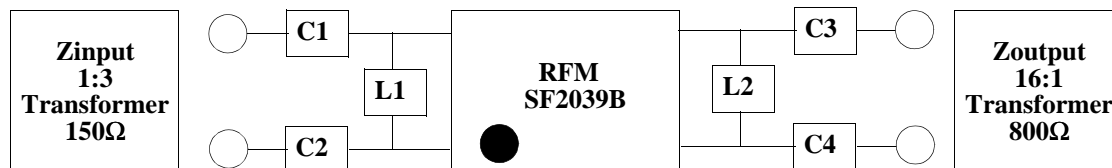


TDM1 Narrowband SAW Matching Circuit

TDM1 Narrowband SAW Matching Values

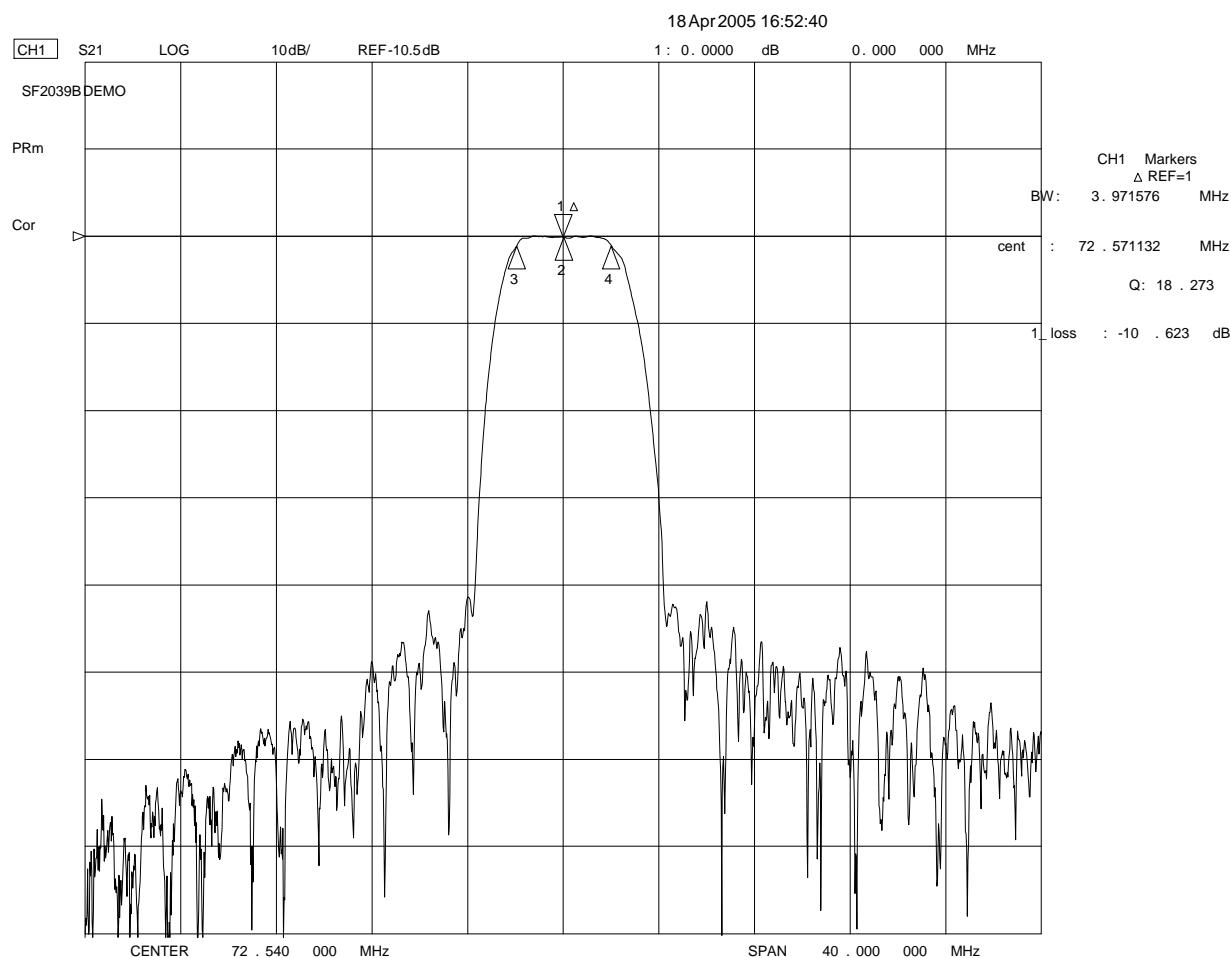
Reference Designator	Value
C5	10 pF
C6	10 pF
L3	330 nH
L4	560 nH
C7	100 pF
C8	100 pF

Matching Circuit and Matching Component Values Used on Filter Demo Board

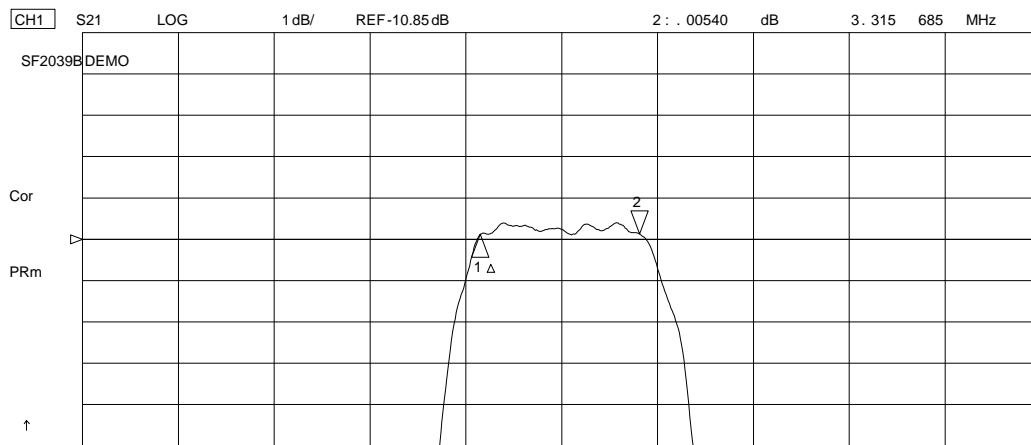


SF2039B
72.540 MHz

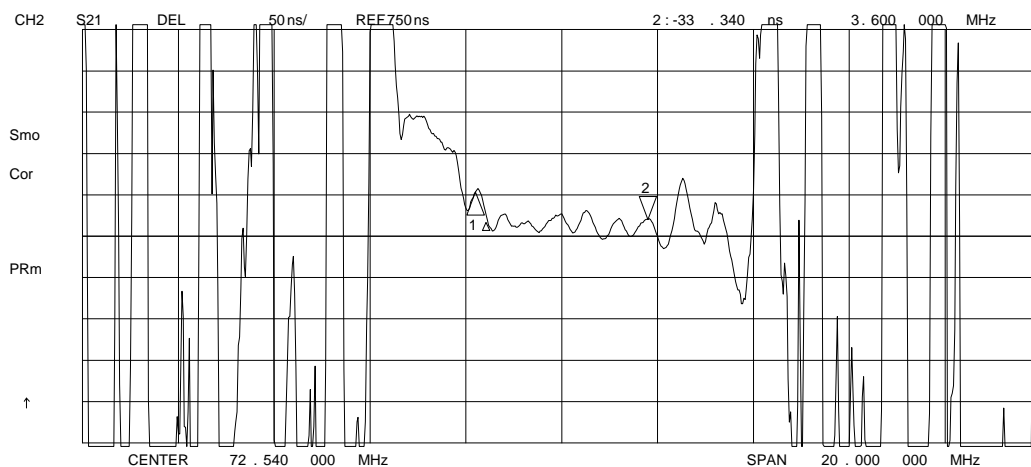
C1 = 10pF
C2 = 10pF
L1 = 330nH
L2 = 390nH
C3 = 18pF
C4 = 18pF



18 Apr 2005 16:59:10



CH1 Markers
Δ REF=1
mean : -10 . 593 dB
s . dev : . 08060 dB
p-p : . 28160 dB



CH2 Markers
Δ REF=1
mean : 766 . 06 ns
s . dev : 11 . 855 ns
p-p : 61 . 340 ns

18 Apr 2005 17:02:37

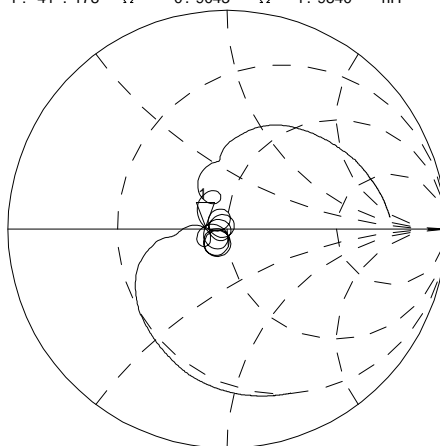
CH1 S11 1UFS 1 : 41 . 178 Ω 0 . 9043 Ω 1 . 9840 nH 72 . 540 000 MHz

SF2039BDEMO

Cor

PRm

↑

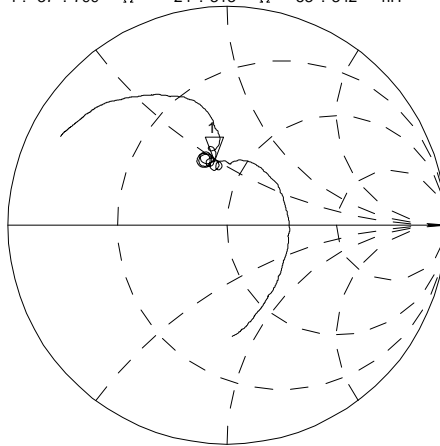


CH2 S22 1UFS 1 : 37 . 799 Ω 24 . 313 Ω 53 . 342 nH 72 . 540 000 MHz

Cor

PRm

↑

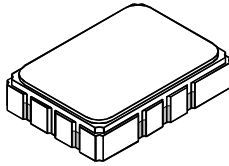


CENTER 72 . 540 000 MHz

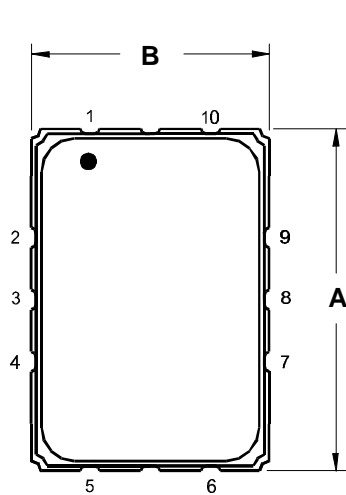
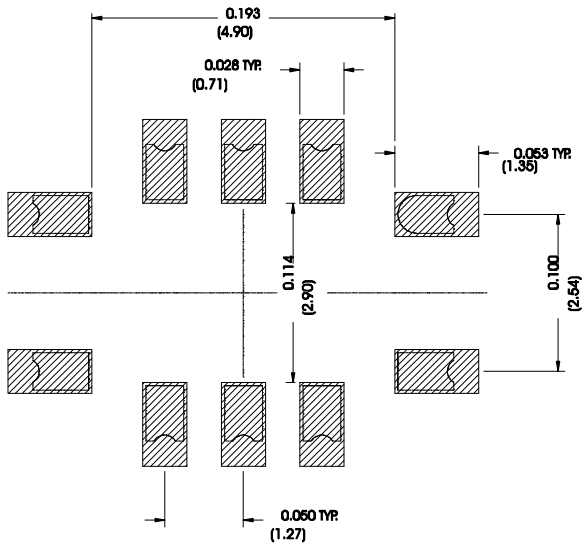
SPAN 20 . 000 000 MHz

SMP-03 Case

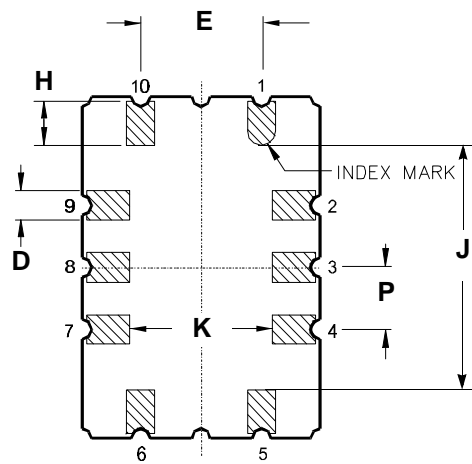
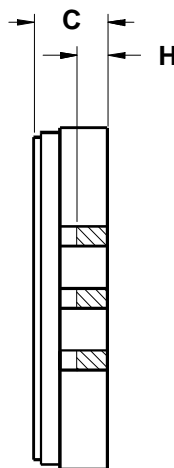
10-Terminal Ceramic Surface-Mount Case 7 x 5 mm Nominal Footprint



Recommended PCB Footprint



TOP VIEW



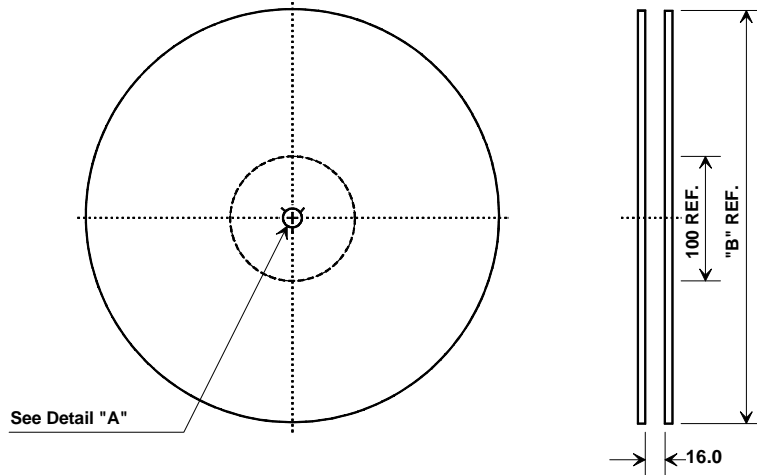
BOTTOM VIEW

Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	6.80	7.00	7.20	0.268	0.276	0.283
B	4.80	5.00	5.20	0.189	0.197	0.205
C		1.65	2.00		0.065	0.079
D	.47	0.60	.73	0.019	0.024	0.029
E	2.41	2.54	2.67	0.095	0.100	0.105
H	0.87	1.0	1.13	0.034	0.039	0.044
J	4.87	5.00	5.13	0.192	0.197	0.202
K	2.87	3.00	3.13	0.113	0.118	0.123
P	1.14	1.27	1.40	0.045	0.050	0.055

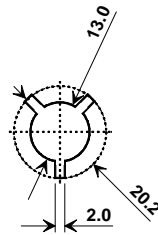
Materials	
Solder Pad Termination	Au plating 30 - 60 ulnches (76.2-152 uM) over 80-200 ulnches (203-508 uM) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 ulnches Thick
Body	Al ₂ O ₃ Ceramic
Pb Free	

Electrical Connections		
Connection		Terminals
Port 1	Input or Return	10
	Return or Input	1
Port 2	Output or Return	5
	Return or Output	6
Ground		All others
Single Ended Operation		Return is ground
Differential Operation		Return is hot

Tape and Reel Specifications



"B "		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	2000



COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	5.5 mm
Bo	7.5 mm
Ko	2.0 mm
Pitch	8.0 mm
W	16.0 mm

